

# SOT1397-8

WLCSP20, wafer level chip-scale package; 20 bumps; 0.4 mm pitch, 2.50 mm x 1.84 mm x 0.5 mm body

25 May 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP20
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	24-5-2018
<b>Manufacturer package code</b>	98ASA01253D

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		-	1.84	-	mm
package width		-	2.5	-	mm
seated height		-	0.5	-	mm
nominal pitch		-	0.4	-	mm
actual quantity of termination		-	20	-	A/A



WLCSP20, wafer level chip-scale package; 20 bumps; 0.4 mm pitch, 2.50 mm x 1.84 mm x 0.5 mm body

## 2. Package outline

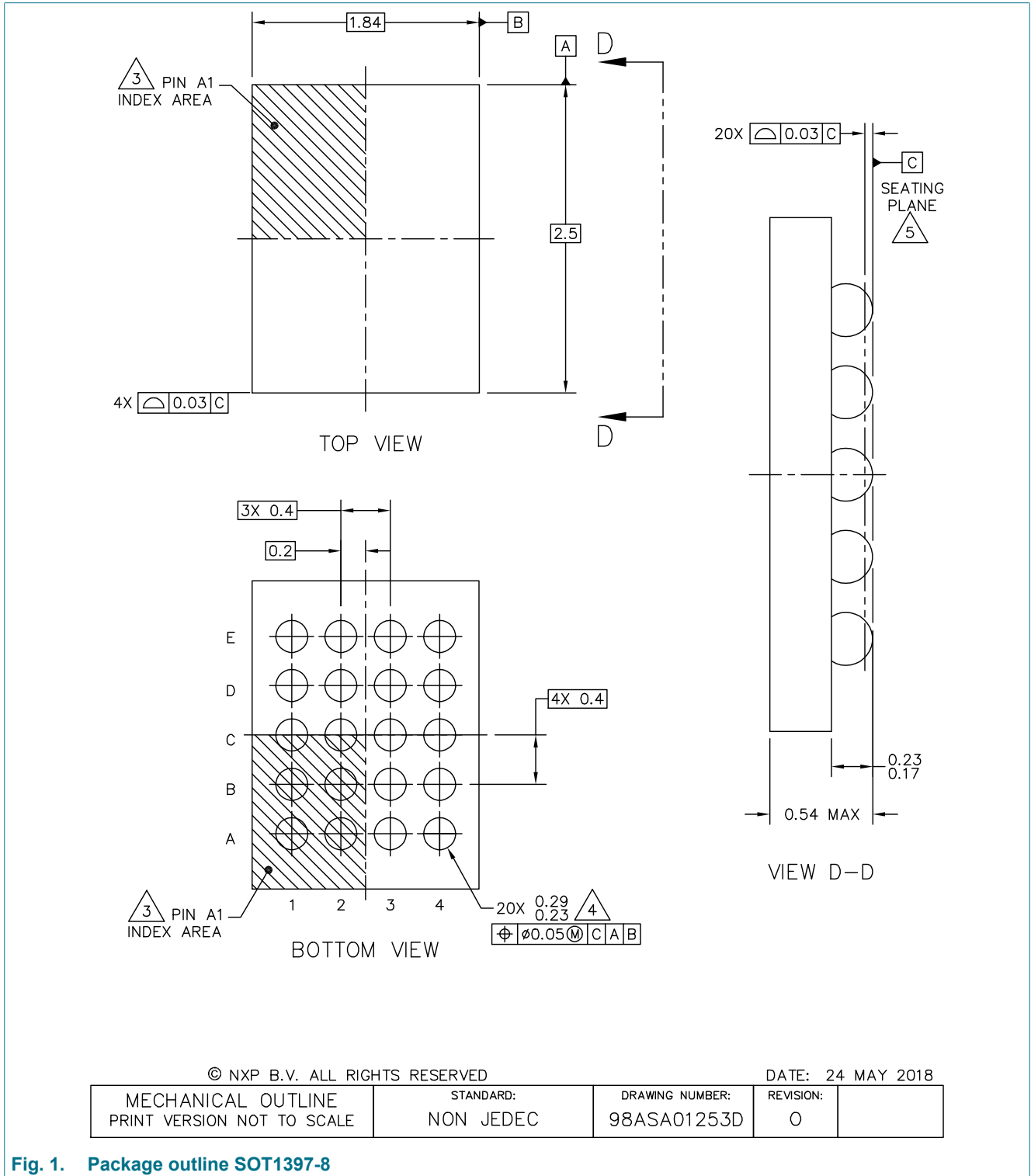


Fig. 1. Package outline SOT1397-8

WLCSP20, wafer level chip-scale package; 20 bumps; 0.4 mm pitch, 2.50 mm x 1.84 mm x 0.5 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 CONFIGURATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

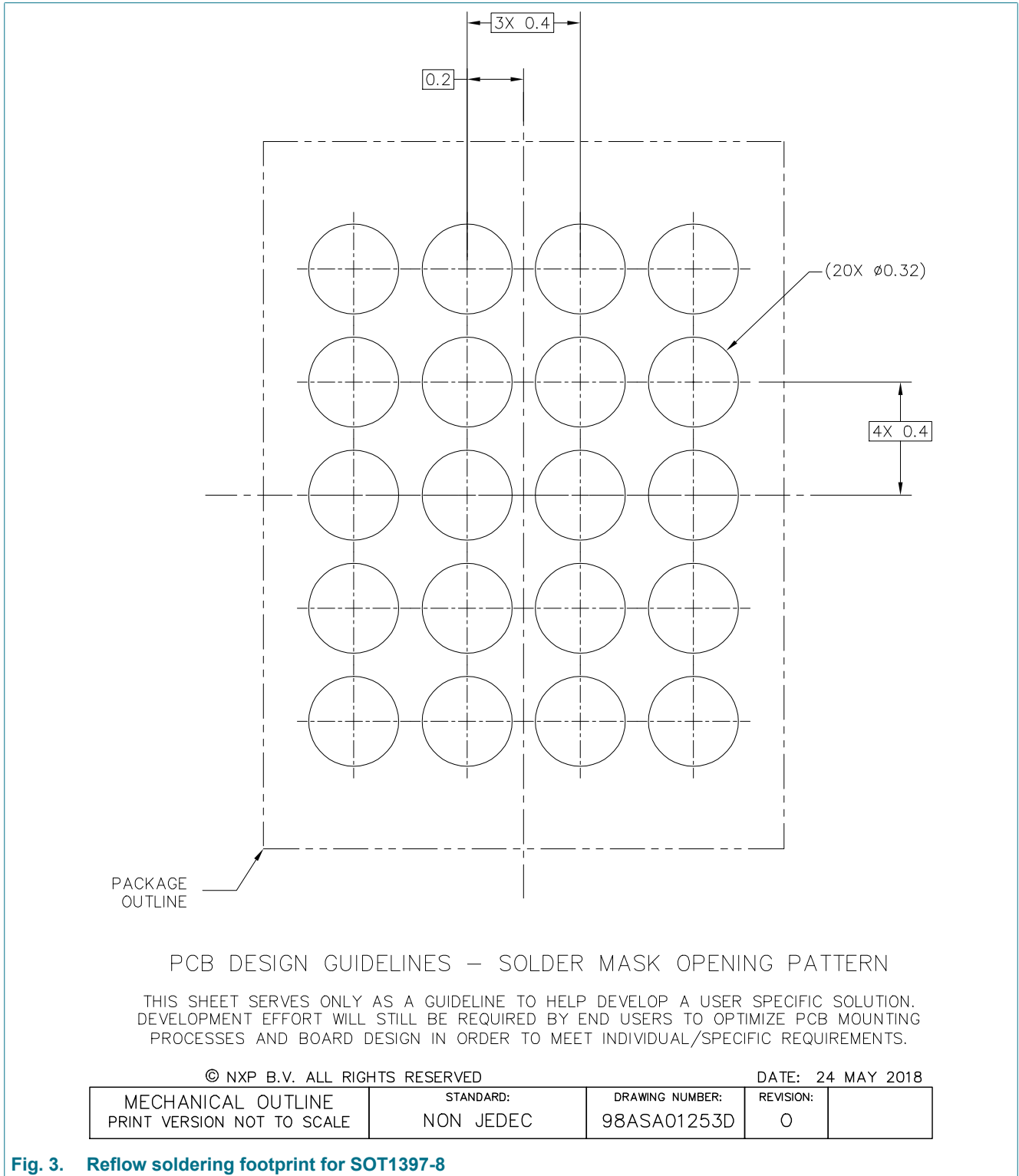
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DATE: 24 MAY 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01253D	REVISION: 0	
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Fig. 2. Package outline note for WLCSP20 (SOT1397-8)

### 3. Soldering



**Fig. 3. Reflow soldering footprint for SOT1397-8**

WLCSP20, wafer level chip-scale package; 20 bumps; 0.4 mm pitch, 2.50 mm x 1.84 mm x 0.5 mm body

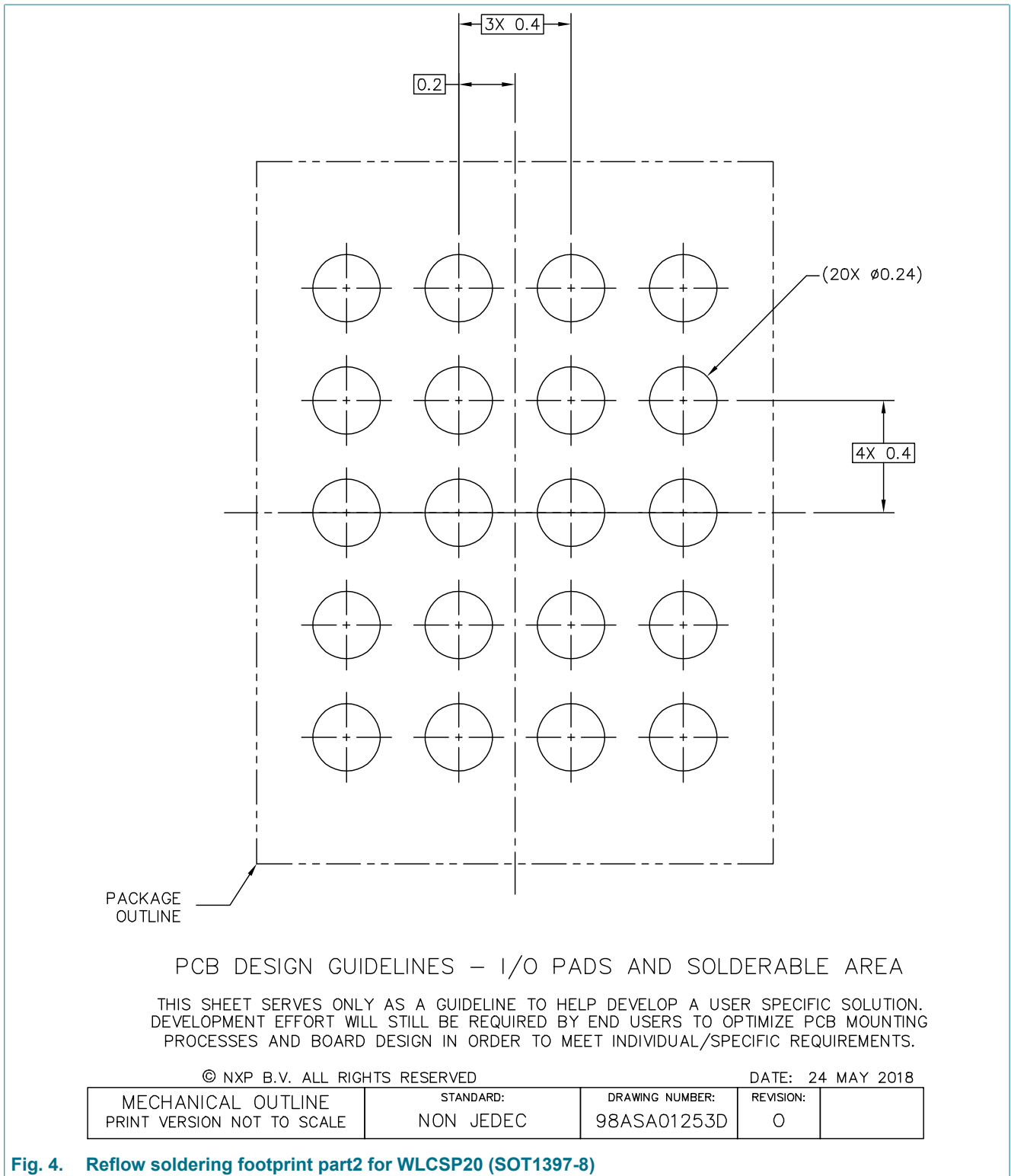


Fig. 4. Reflow soldering footprint part2 for WLCSP20 (SOT1397-8)

WLCSP20, wafer level chip-scale package; 20 bumps; 0.4 mm pitch, 2.50 mm x 1.84 mm x 0.5 mm body

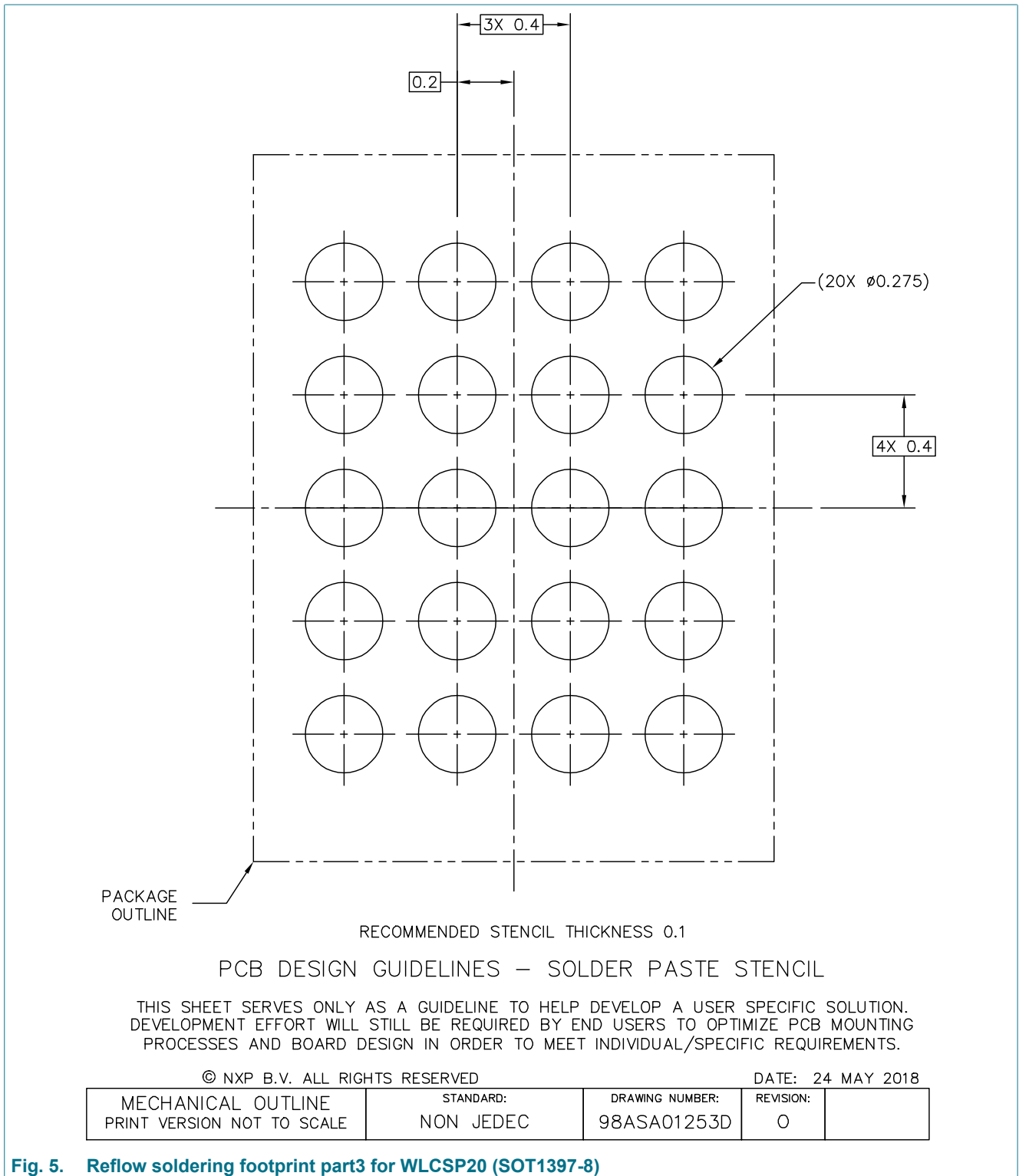


Fig. 5. Reflow soldering footprint part3 for WLCSP20 (SOT1397-8)

## 4. Legal information

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